Charge collection and laser measurements on double-sided 3D strip sensors irradiated up to 2*10¹⁶ n_{eq}/cm²

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Gian-Franco Dalla Betta^{1,2}, Christopher Betancourt³, Maurizio Boscardin⁴, Gabriele Giacomini⁴, Karl Jakobs³, Susanne Kühn³, Besnik Lecini¹, Roberto Mendicino^{1,2}, *Riccardo Mori*³, Ulrich Parzefall³, Marco Povoli¹, Maira Thomas³, Nicola Zorzi⁴

23rd RD50 workshop, CERN, 2013.11.15

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- 1: Dipartimento di Ingegneria Industriale, Università degli Studi di Trento, Italy.
- 2: INFN Sezione di Padova, Gruppo Collegato di Trento, Italy.
- 3: Physikalisches Institut, Albert-Ludwigs Universität Freiburg, Germany.
- 4: Fondazione Bruno Kessler, Centro per i Materiali e i Microsistemi (FBK-CMM), Italy.



Introduction:

- recent studies;
- Motivations;
- looking forward...
- •Materials:
 - sensors;
 - set-ups.

•Methods:

- calibration;
- measurements: I-V, punch-through, β-source, laser;
- analysis details.
- •Experimental results and discussion:
 - I-V and punch-through;
 - β-source;
 - laser.

•Summary and outlook.



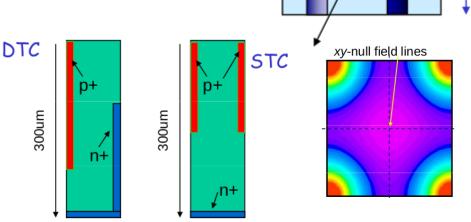
Recent studies:

- 3D sensors main features:
 - Short "collection"-path, long "generation"-path => radiation-hard (up to 5*10¹⁵ n_{eq}/cm² and beyond[1]).
 3D
 - Dead zones between same type columns => non-uniform collection. p*
 - Narrow bulk => high capacitance => high noise.
 - Complex layout => challenging fabrication.
- Technologies:
 - Original 3D[2]:
 - Exploit of the advantages.
 - Complexity.
 - Single-type column (STC):
 - Much simpler.
 - Large dead zones.
 - Double-type columns (DTC):
 - Better performances than STC.
 - Simpler than the originals.
- Charge multiplication observed[3].
- First production of 3D pixels accomplished at FBK and CNM with DTC [4].

[1] The ATLAS IBL Coll., Jinst 7, 2012.

- [2] Dalla Betta et al., PoS Vertex 2012, 2012.
- [3] Köhler et al., NIMA 659, 2011.

[4] Da Via et al., NIMA 649, 2012.





300 µm

50 μm

3



•Motivations:

- Test radiation hardness up to higher fluences in view of the HL-LHC
 - => Samples highly irradiated.
 - Despite the higher noise, test the signal to noise ratio (at those fluences):
 - => β -source measurements.
 - Interest on the spatial uniformity with the improved technology:
 - => laser measurements.

- Looking forward...
 - How to exploit the charge multiplication?
 - How important is the non-uniformity?
 - Is a new technology required?

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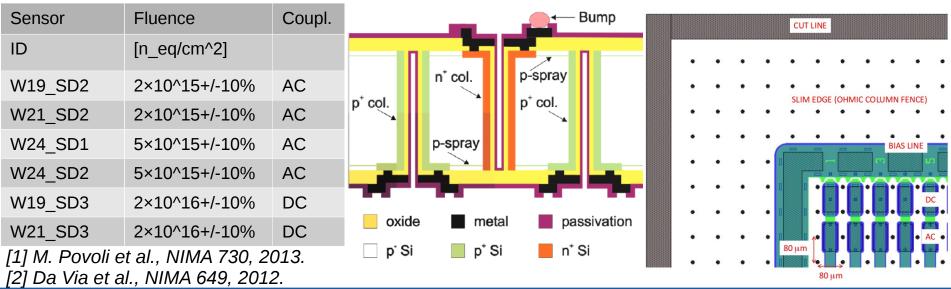
Materials

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•Samples[1]:

5

- Double-sided 3D <u>strip</u> sensors (<u>FBK ATLAS production wafers</u> [2]). (Strips => easier testing with standard readout electronics.)
- 4", FZ, <100>, p-type, 230+/-20 um thickness, ~20 kΩ*cm.
- 102 strips ~8 mm length, with 80 um pitch between same type columns and $40\sqrt{2}$ ~56 um between different column types, slim edges.
- Columns passing completely through the substrate, ~11 um diameter, not filled by polysilicon.
- P-spray, front side strip connection by n+ diffusion (AC coupling, punch-trough biasing but readout with R-C fanins) or combination of metal and diffusion (DC coupling, readout by R-C fanins).
- Irradiated at 25 MeV protons (NIEL hardness factor of 1.85) at the Karlsruhe Compact Cyclotron (annealing only due to holding during experiments).



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Materials

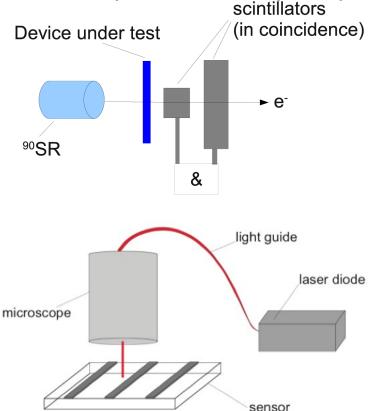
•Set-ups:

- I-V:
 - Standard probe station, before, through AliBaVa, after irradiation.
- Punch-through:

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- Stated the very high resistance before punch-trough, measurements made with a custom circuit (inverted amplifier with operational amplifier).
- β-source:
 - AliBaVa (Beetle chip).
 - 37 Mbq ⁹⁰Sr source.
 - 2 scintillator in coincidence.
- Laser:
 - AliBaVa.
 - 974 nm => ~90 um penetration depth, ~4.5 um FHWM.
 - Horizontal plane motorized stage.
- Simulations:
 - TCAD with Synopsis Sentaurus, modified "Perugia" model [1].

[1] Pennicard et al., NIMA 592, 2008.





6



Methods

•Procedures:

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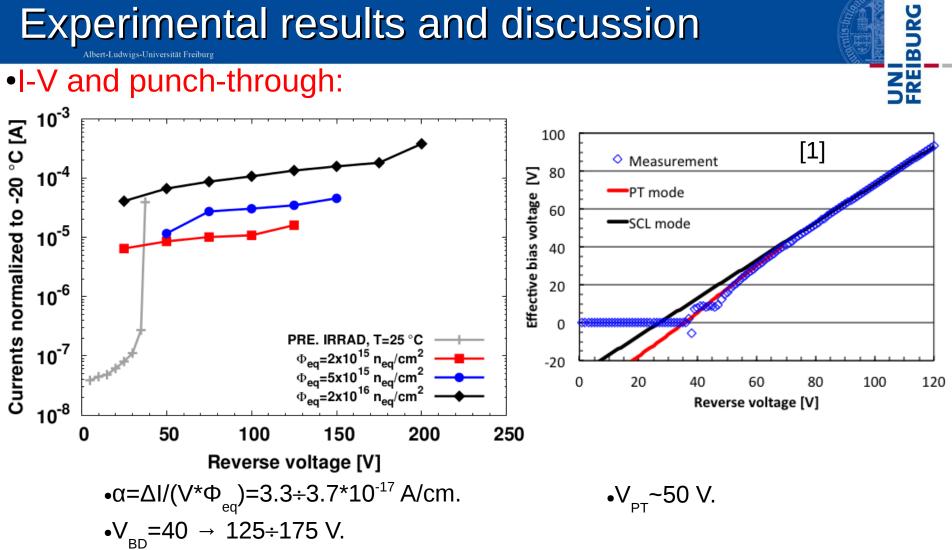
- β-source:
 - Calibration:

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- Sample: unirradiated sensor of known thickness.
- Method: MPV vs. temperature; assumption of the generated charge (0.027ln(thick.)+0.176 [1]); linear fit of the gain vs. temperature.
- Measurements:
 - AliBaVa "kazu" configuration (>25 ns peaking time); $T \in [-41, -27]$ °C, RH<~10%.
 - Runs: pedestals+noise+source, at different voltages.
- Analysis details:
 - Residual cut<~70 strips; time cut=10 ns around the peak; Clustering: seed cut also down to 2, neighbour cut also to 1.5 (maintaining clear signal).
- Laser:
 - No calibration => relative measurements.
 - Measurements:
 - AliBaVa standard configuration (~25 ns peaking time); T<-35 °C, RH<~10%.
 - Runs: pedestals+noise+synch.+scan, at different voltages.
 - Analysis details:
 - Sometimes realignment/rebinning (bilinear interpolation, I-order).
 - Representation of the sum of two neighbour strips or a single strip.

[1] Meroli et al., Jinst 6 P06013, 2012.

•I-V and punch-through:



Leakage current and break-down voltage increase with the fluence as expected.

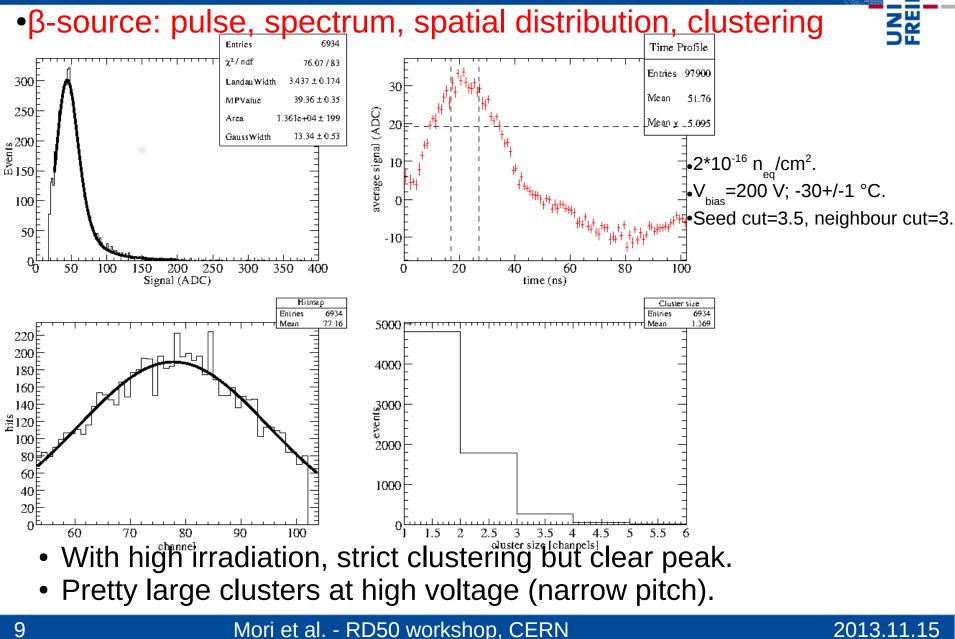
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Punch-trough biasing still effective after irradiation.

[1] Betancourt et al., IEEE TNS 59(3), 2012.

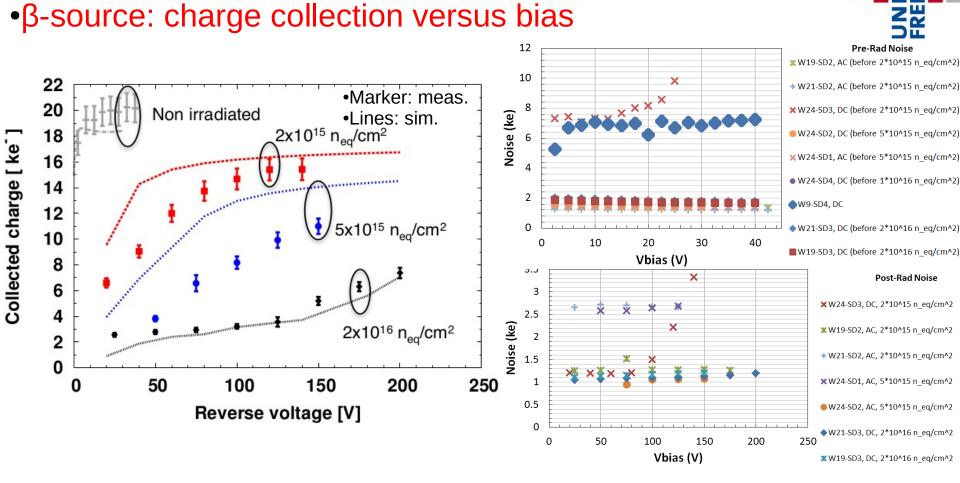
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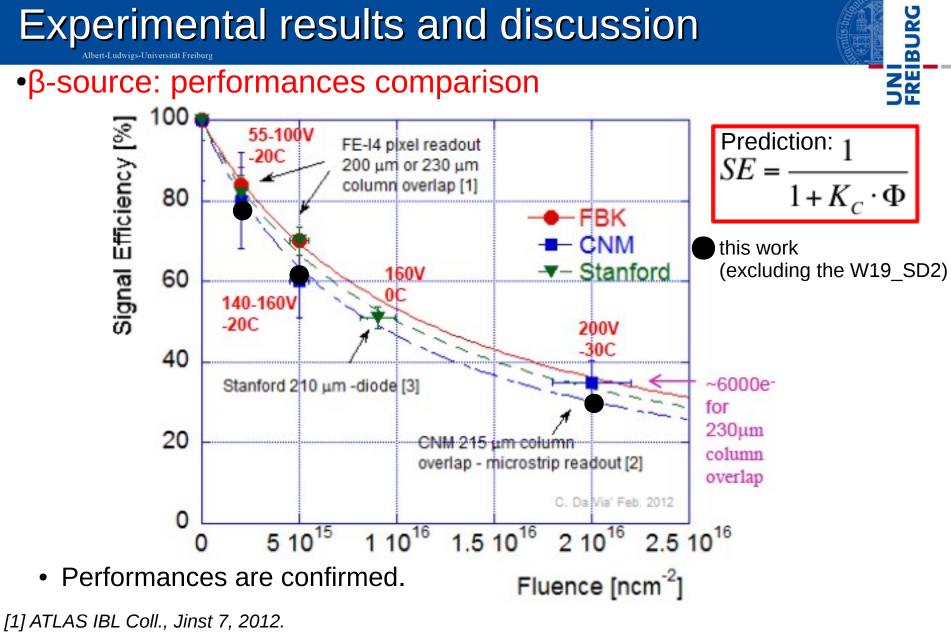
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- Charge collection in agreement with simulations. Significant also at low voltages (see 20 V, $2*10^{15} n_{eq}/cm^2$).
- No charge multiplication (maybe at $2*10^{16} n_{eq}/cm^2$).
- Noise dominated by electronics, leakage current? (Interstrip/bulk capacitance<10%.)

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•β-source: performances comparison

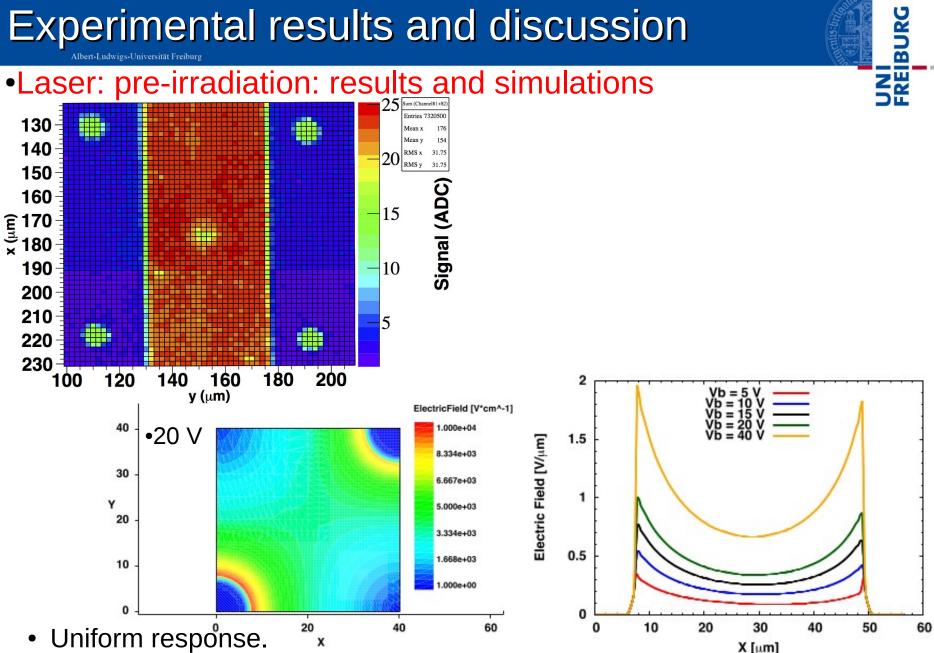


[2] Köhler et al., NIMA 659, 2011. [3] Da Via et al., NIMA 604, 2009.

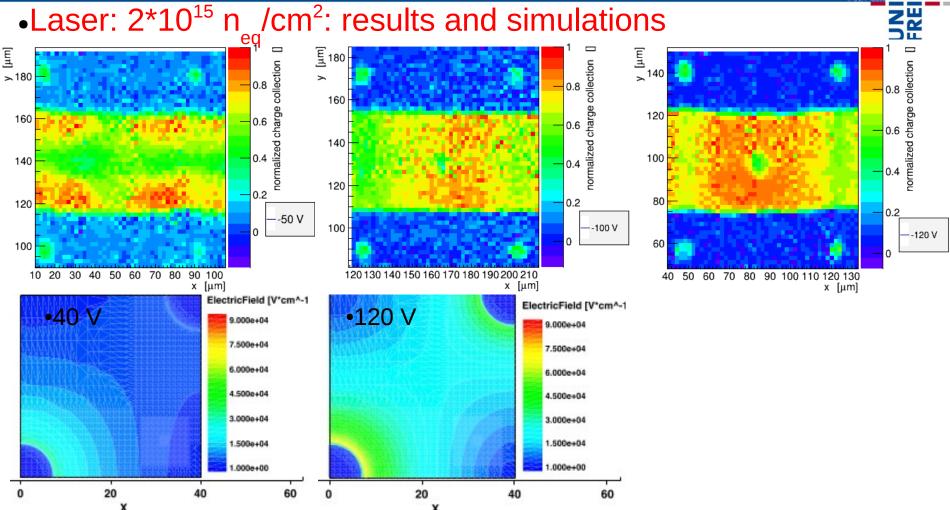
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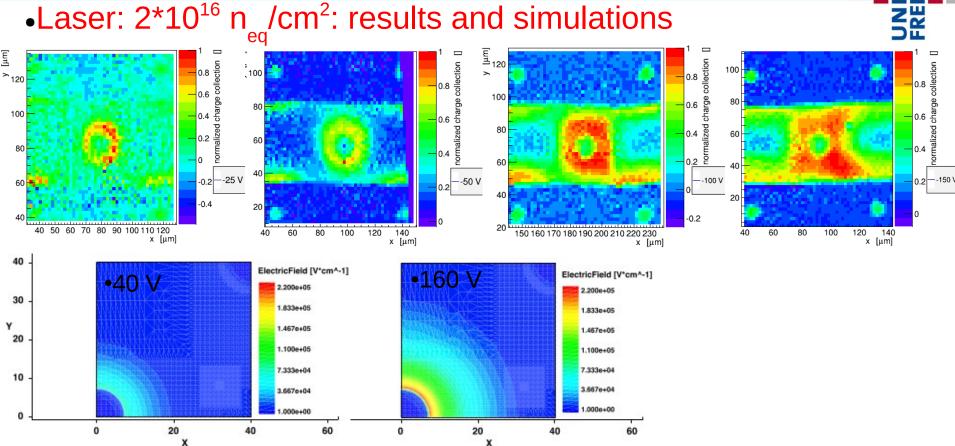


 Significant change with bias: collection from junction columns to in between those of the same strip => "compensation" effect: sum for same strip, subtraction for neighbours.

Experimental results and discussion •Laser: 2*10¹⁵ n_/cm²: discussion: "compensation" effect NH E 180 Large negative zones 0.6 160 From Ramo's Th. •E ~<0 140 •E<<0 Weighting field × •vel<0 100 V •100 V, top => I(t:low)<0 -0.1 120 130 140 150 160 170 180 190 200 210 -50 V x [µm] -50 V •junction columns profile •ohmic columns profile -100 V -100 V -100 V (Channel 94 charge) -100 V (Channel 94 charge) collection normalized charge collection 0.8 -100 V (Channel 95 charge) -100 V (Channel 95 charge) 0.6 -120 V ormalized charge -120 V 0.4 0.2 h50_py_colpn Entries 151 h50 py colp -1.245 Mean 151 Entries 18.6 RMS 20 60 80 Mean 42.7 y [μm] RMS Significant compensation effect due to limited integration time and hole deficit[1]. [1] Pöhlsen, RD50 workshop talk 2013.11.14, Experimental study of the Si-SiO2 interface region... 20.67 14

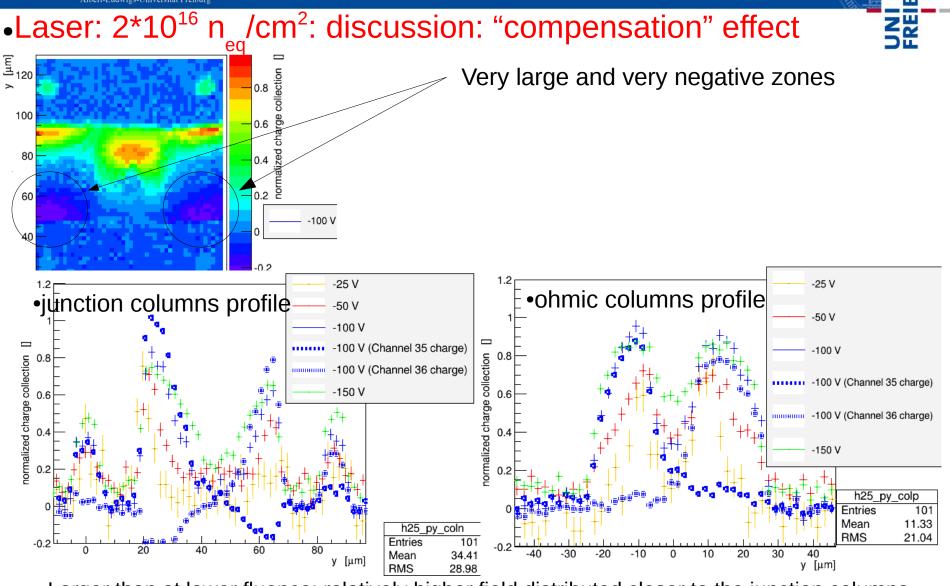
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- Large dead zones also at 160 V (with ~20% collection).
 - NOTE: collecting 5 ke- at 150 V, an average unit cell collection of 50% means peaks collecting effectively 10 ke-!
- Significant collection at the ohmic columns also at low voltage. Double-junction on p-type??? Not predicted!

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• Larger than at lower fluence: relatively higher field distributed closer to the junction columns.

•Laser: 2*10¹⁶ n_{eq}/cm²: comparison with CNM sensors



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•3D irradiated at KIT.

•~285 um thickness, ~215 um columns overlapping.

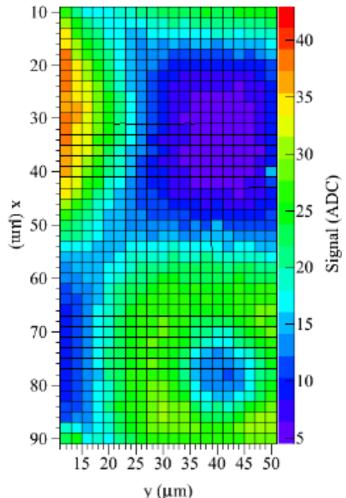
•~56 um column pitch

•Same set-up.

•2*10¹⁶ n_{eq}/cm². •100 V.

- (Measured charge multiplication.)
- Similarly high collection at the ohmic columns.

[1] Köhler et al., NIMA 659, 2011.



Experimental results and discussion •Laser: 2*10¹⁶ n_{eq}/cm²: discussion: hole trapping and ballistic deficit Profile on the line (n+)-(p+)Sum (Channel35+36) aligned onlin 35 Entries Mean 38.19 60 normalized charge collection RMS 20.9 -25 V -50 V -100 V 0.8 40 distance -150 V 0.6 20600.4 both 0.2 collected n+ only e-50 10 20 30 40 60 distance [µm]

• With the low field, the slower holes are not integrated and are more prone to recombine. Increasing the bias, the effect is reduced.

Summary and outlook

•Motivations:

Results:

- Test radiation hardness up to 2*10¹⁶ n_{eq}/cm²: charge collection, spatial uniformity.
 New sensors DTC: reasonable increase in the brack of irradiation achieved.
- Punch-through effective at $2*10^{15} n_{eq}/cm^2$.
- Charge collection as expected. Significant also at low voltages (6 ke- @ 20 V, • $2*10^{15} n_{eq}/cm^2$). No charge multiplication observed.
- Collection still far to be uniform at high irradiation fluences:
 - Compensation effect due to limited integration time and holes deficit.
 - For $2*10^{15} n_{eq}/cm^2$ increasing the bias the highest collection moves from around the junction columns to in between them; still due to compensation.
 - High collection close to the ohmic columns: determined by the amount of the holes contribution to the overall signal (how big deficit).
- •Outlook:
 - Smaller inter-electrode spacing to have more uniform collection at lower voltages. Higher break-down voltage needed (encouraging results in new FBK samples[1]).
 - Changing integration time to investigate the compensation effect and the hole deficit.
 - Test beam or X-rays!!!

[1] Dalla Betta et al., IEEE NSS N41-1, 2013.

Summary and outlook

•Motivations:

UNI FREIBU • Test radiation hardness up to $2*10^{16} n_{eq}/cm^2$: charge collection, spatial uniformity.

Results:

- New sensors DTC: reasonable increase in the breakdown voltage before and after irradiation achieved.
- Punch-through effective at $2*10^{15} n_{eff}/cm^2$.
- Charge collection as expected. Significant also at low voltages (6 ke- @ 20 V, • $2*10^{15}$ n_n/cm²). No charge multiplication observed.
- Collection still far to be uniform at high irradiation fluences:
 - Compensation effect due to limited integration time and holes deficit.
 - For $2*10^{15} n_{eq}/cm^2$ increasing the bias the highest collection moves from around the junction columns to in between them; still due to compensation.
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- Changing integration time to investigate the compensation effect and the hole deficit. Thank
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[1] Dalla Betta et al., IEEE NSS N41-1, 2013.



- •Sensor details.
- •Clustering effect.
- •Hole deficit for $2*10^{15} n_{eq}/cm^2$.
- •Tilted cell.





Spares: sensors details

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•Coupling details:

- AC: biased by punch-through from the bias line and have integrated coupling capacitors
- DC: can be used via an external R-C fan-in (R= 1 M Ω , C=275 pF).

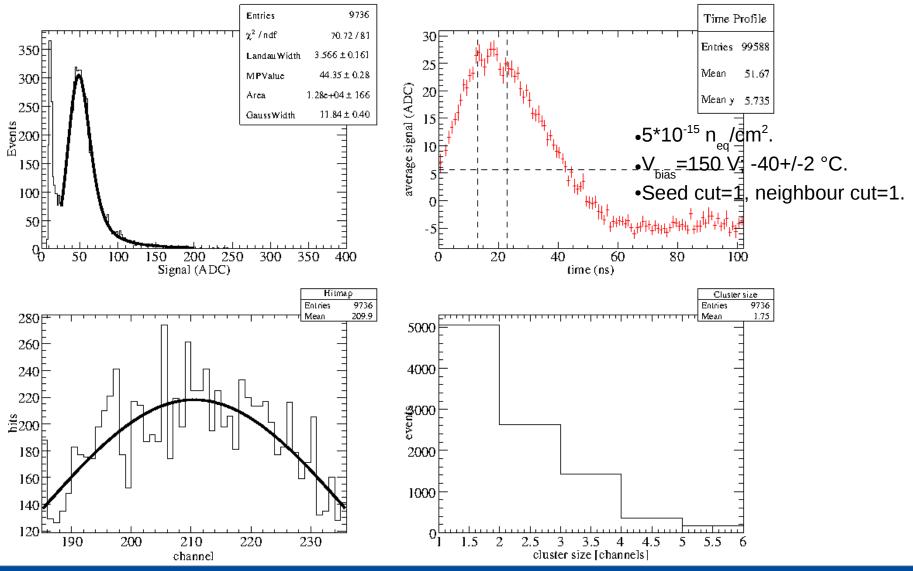
•Methods details:

Results were qualitatively similar, but in the AC configuration, the non-optimized thickness of the coupling oxide layer (which is about 1 µm due to other process constraints) caused the coupling capacitance (~8 pF) to be insufficient, and higher signal and signal/noise values were obtained by using R-C chips. Thus, although the punch-through bias was proved to properly work also after irradiation, all functional tests discussed here were carried out by using external R-C chips.

Spares: clustering effect (1)

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•β-source: pulse, spectrum, spatial distribution, clustering



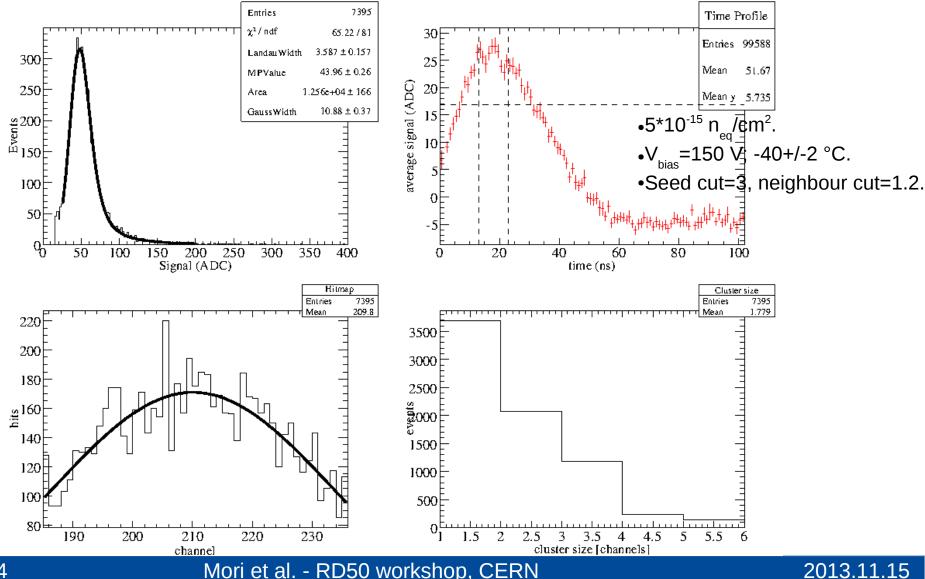
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Spares: clustering effect (2)

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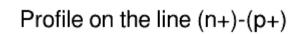
•β-source: pulse, spectrum, spatial distribution, clustering

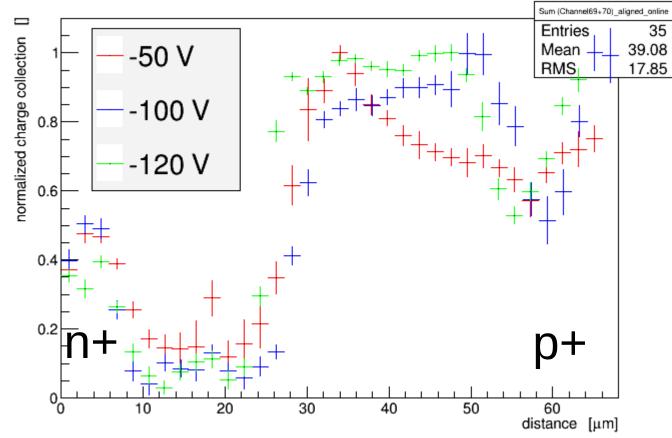


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Spares: hole deficit at 2*10^15 n_eq/cm^2 •Laser: 2*10¹⁵ n_{eq}/cm²: discussion: hole trapping and ballistic

deficit





Before depletion, holes still collected and/or much lower electron • contribution close to the ohmic columns (relative collection!!!).

Spares: tilted cell

